

AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior versions, and listings, of claims in the application:

1. (Currently amended) A computerized method of calculating a custom die price, comprising:
 - providing an interface for designating base parameters;
 - obtaining the base parameters;
 - selecting a base die based on the base parameters;
 - creating a reference die based on a design methodology and the base parameters;
 - calculating a complexity factor based on designated custom parameters and the reference die; and
 - calculating the custom die price based on the base die, the custom parameters and the complexity factor.
2. (Original) The method of claim 1, wherein the base parameters include a technology, an X-dimension, a Y-dimension and a number of levels of metal.
3. (Currently amended) The method of claim 1, wherein the selecting step includes:
 - providing a set of possible base dies based on the ~~designated chip~~ base parameters; and
 - selecting the base die from the set of possible base dies.

4. (Currently amended) The method of claim 1, wherein the reference die is a most complex die available based on the ~~designated~~ base parameters.
5. (Original) The method of claim 1, wherein the custom parameters include a core, an oxide level, a solder type, a cell logic circuit count, register array parameters and memory parameters.
6. (Original) The method of claim 1, wherein the calculating a complexity factor step includes:
- creating a custom die having the base parameters and the custom parameters;
 - determining a custom die yield;
 - determining a reference die yield; and
 - dividing the custom die yield by the reference die yield to provide the complexity factor.
7. (Original) The method of claim 1, wherein the calculating the custom die price step includes:
- calculating a base die price for the base die;
 - providing the custom die price by modifying the base die price based on the custom parameters; and
 - adjusting the custom die price using the complexity factor.
8. (Original) The method of claim 1, further comprising calculating a chip price based on the custom die price and designated package parameters.

9. (Original) The method of claim 8, further comprising:

designating a chip quantity; and
adjusting the chip price based on the chip quantity.

10. (Original) A computerized method of calculating a custom die price, comprising:

designating base parameters;
calculating a base die price based on the base parameters;
creating a reference die based on a design methodology and the base parameters;
creating a custom die by designating custom parameters;
calculating a complexity factor based on the custom die and the reference die; and
calculating the custom die price based on the base die price, the custom die and the complexity factor.

11. (Original) The method of claim 10, wherein the designating step includes:

providing a set of possible base dies; and
selecting a base die from the set of possible base dies.

12. (Original) The method of claim 11, wherein the designating step further includes selecting a first base parameter, wherein each possible base die includes the first base parameter.

13. (Original) The method of claim 10, wherein the calculating a complexity factor step includes:

determining a custom die yield based on the custom die;

determining a reference die yield based on the reference die; and

dividing the custom die yield by the reference die yield to provide the complexity factor.

14. (Original) The method of claim 10, wherein the calculating the custom die price step includes:

modifying the base die price based on the custom parameters to provide the custom die price; and

adjusting the custom die price using the complexity factor.

15. (Original) The method of claim 10, further comprising calculating a chip price based on the custom die price and designated package parameters.

16. (Original) The method of claim 15, further comprising:

designating a chip quantity; and

adjusting the chip price based on the chip quantity.

17. (Original) A system for determining a custom die price, comprising:

a base die system for designating base parameters;

a reference die system for creating a reference die based on the base parameters and a design methodology;

a custom die system for designating custom parameters;

a complexity system for calculating a complexity factor based on the custom parameters and the reference die; and

a calculation system for calculating the custom die price based on the base parameters, the custom parameters and the complexity factor.

18. (Original) The system of claim 17, further comprising a packaging system for calculating a chip price based on the custom die price and designated packaging parameters.

19. (Original) The system of claim 18, further comprising a volume system for adjusting the chip price based on a designated quantity.

20. (Original) A computer program product comprising a computer useable medium having computer readable program code embodied therein for determining a custom die price, the program product comprising:

program code for designating base parameters;

program code for calculating a base die price based on the base parameters;

program code for creating a reference die based on a design methodology and the base parameters;

program code for creating a custom die by designating custom parameters;

program code for calculating a complexity factor based on the custom die and the reference die; and

program code for calculating a custom die price based on the base die price, the custom die and the complexity factor.

21. (Original) The computer program product of claim 20, wherein the program code for designating base parameters includes:

program code for providing a set of possible base dies; and

program code for selecting a base die from the set of possible base dies.

22. (Original) The computer program product of claim 21, wherein the program code for designating base parameters further includes program code for selecting a first base parameter, wherein each possible base die includes the first base parameter.

23. (Original) The computer program product of claim 20, wherein the program code for calculating a complexity factor includes:

program code for determining a custom die yield based on the custom die; and

program code for determining a reference die yield based on the reference die.

24. (Original) The computer program product of claim 20, wherein the program code for calculating a custom die price includes:

program code for calculating a custom die price for the custom die using the base die price and the custom die; and

program code for adjusting the custom die price using the complexity factor.

25. (Original) The computer program product of claim 20, further comprising program code for calculating a chip price based on the custom die price and designated package parameters.

26. (Original) The computer program product of claim 20, further comprising:

program code for providing an interface for designating a chip quantity; and

program code for adjusting the chip price based on the chip quantity.